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## **Declaration For U.S. Patent Application**

As a below named inventor, I hereby declare that: My residence, post office address and citizenship are as stated below my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled (Insert Title) INTEGRATED CIRCUIT DEVICE MODULE the specification of which (Check one 1. Ki is attached hereto. of blocks 2. □ was filed on 1, 2 or 3. International PCT Application Serial No. See note A and was amended on \_\_ on back of (if applicable) this page) 3. □ was filed on U.S. Application Serial No. and was amended on \_ (if applicable) I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s). as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a). I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed: Priority Claimed 10-007771 Japan 19/01/1998 ΔiXYes □ No (Day/Month/Year Filed) (Number) (Country) (List prior foreign ☐ Yes ☐ No applications. (Day/Month/Year Filed) (Country) (Number) See note B ☐ Yes ☐ No on back of (Number) (Country) (Day/Month/Year Filed) this page) (See Note C on back ☐ See attached list for additional prior foreign applications of this page) I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: (List prior U.S. Applications) (Application Serial No.) (Filing Date) (Status) (patented, pending, abandoned) (Application Serial No.) (Filing Date) (Status) (patented, pending, abandoned) And I hereby appoint as principal attorneys David T. Nikaido, Reg. No. 22,663; Charles M. Marmelstein, Reg. No. 25,895; George E. Oram, Jr., Reg. No. 27,931; Robert B. Murray, Reg. No. 22,980; Martin S. Postman, Reg. No. 18,570; E. Marcie Emas, Reg. No. 32,131; Douglas H. Goldhush, Reg. No. 33,125; Kevin C. Brown, Reg. No. 32,402; Monica Chin Kitts, Reg. No. 36,105; Sharon N. Klesner, Reg. No. 36,335 and Richard J. Berman, Reg. No. 39,107. Please direct all communications to the following address: NIKAIDO, MARMELSTEIN, MURRAY & ORAM LLP Metropolitan Square 655 Fifteenth Street, N.W., Suite 330 - G Street Lobby Washington, D.C. 20005-5701 (202) 638-5000 Fax: (202) 638-4810 I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and

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belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that

such willful false statements may jeopardize the validity of the application or any patent issued thereon.